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## ABSTRACT OF THE DISCLOSURE

A photo-sensing device package and the method of packaging such device is provided. The package includes an assembly portion having a substrate formed of a material substantially transparent to light within a predetermined range of wavelengths and a sensing portion having at least one photo-sensing die photo-electronically transducing light within the predetermined range of wavelengths. The assembly portion is formed with at least one metal layer disposed on the substrate about a front surface region thereof, and at least one passivation layer formed to extend over the metal layer. The passivation layer is patterned to define a plurality of first and second access openings respectively about a plurality of first solder wettable pads and at least one second solder wettable pad on the metal layer. Each of the first solder wettable pads is joined by a first solder joint to a solder bump pad formed on the sensing portion, while the second solder wettable pad is joined by a second solder joint to external circuitry.